

GENERAL PROCESS AND OPERATION SPECIFICATION

Diener Plasma Cleaner

I. SCOPE

The purpose of this document is to describe the requirements and basic operating instructions for Diener Plasma Cleaner. This tool is intended for general purpose use to remove the organic contaminations from the substrate surface and perform a descum after lithography. It can process the substrate ranging from small pieces to 6-inch.

II. SAFETY

- a. You must be trained and signed off to use this equipment.
- b. If you are unsure about any procedure or indication while operating this equipment, contact a staff member or trainer for assistance.

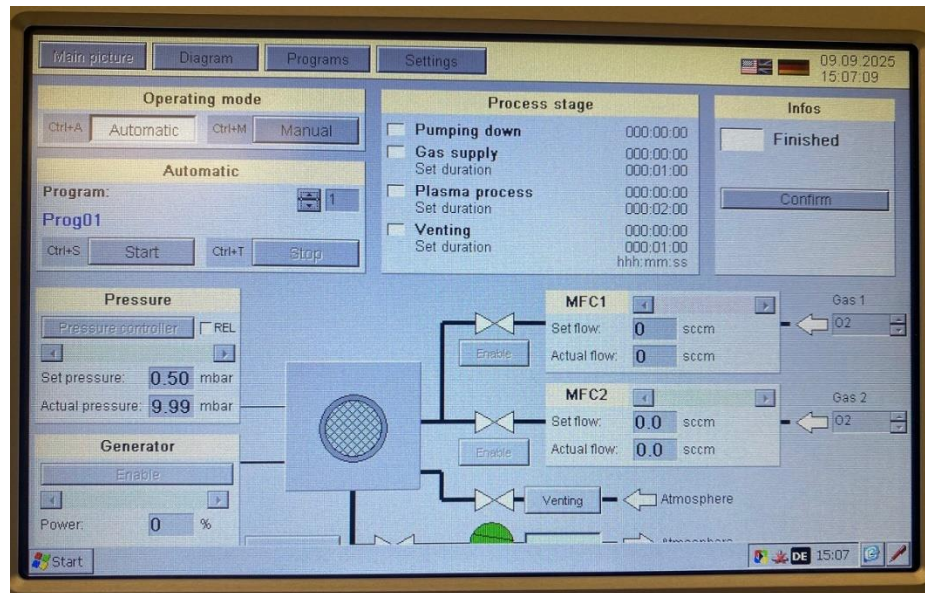
III. OPERATION

1. Start the iLab connection and check the relay light is on.

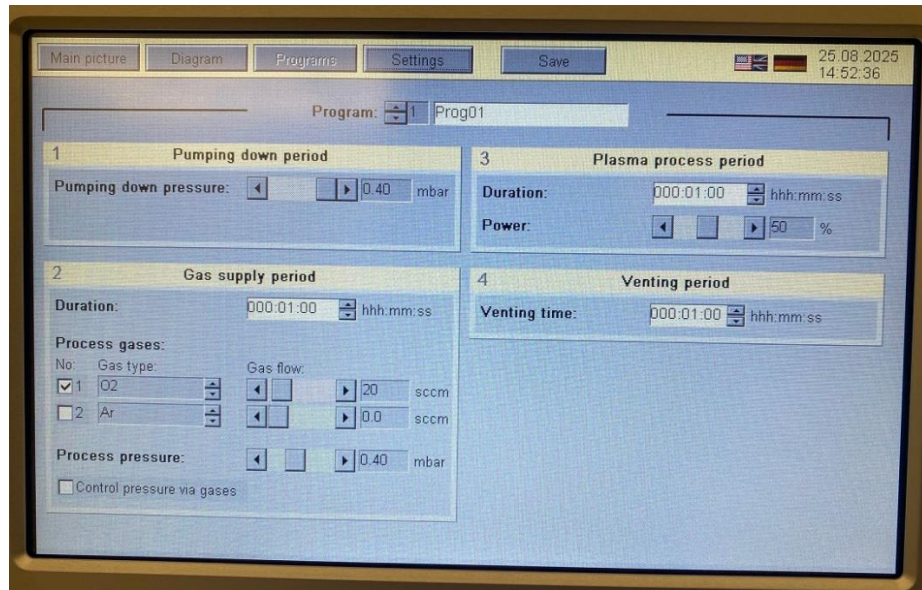


2. Turn on the power button on the back of the machine and then turn on the pump.
3. Use the pen to point “Start” in the display, then point “Settings”, “Taskbar and Start Menu”, “Auto hide”, and “OK”.
4. Open the door, load the wafer or sample onto the plate, and close the door

5. Select the Program (recipe).
6. Use the pen to point “Start” to start the selected program.
7. If it is needed, point “Programs” to change the parameters.



8. Point “Save” after the parameters have been changed.
9. Point “Main picture”.
10. Point “Start” to start the recipe.
11. Wait for the recipe to complete, then the “Finished” will flash.
12. Open the door, unload the wafer or sample from the plate, and close the door.



13. Turn off the pump and then turn off the machine.

14. Input the log sheet and stop the iLab connection.

Approvals:

Technical Manager Signature: Sandra G Malhotra

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Revision History:

Revision	Author	Date
Original Issue	Yaguang Lian	10 September 2025